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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Thomas Nuebel	04/20/2007
Oliver Schilling	04/20/2007
Reinhold Spanke	04/20/2007

RECEIVING PARTY DATA

Name:	Infineon Technologies AG	
Street Address:	StMartin-Str. 53	
City:	Muenchen	
State/Country:	GERMANY	
Postal Code:	D-81669	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11680881

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NAME OF SUBMITTER: Chris Ledel

Total Attachments: 3

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PATENT REEL: 019357 FRAME: 0612

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> PATENT REEL: 019357 FRAME: 0613

ASSIGNMENT

For good and valuable consideration, I, **Thomas Nuebel**, a citizen of Germany, residing at A.-Hillebrand-Weg 12, 59581 Warstein, Germany, **Oliver Schilling**, a citizen of Germany, residing at Karl-Pieperstr. 16, 59581 Warstein, Germany, and **Reinhold Spanke**, a citizen of Germany, residing at Heinrich-Luebke-Str. 2, 59909 Bestwig, Germany, hereinafter individually and collectively referred to as "Assignor";

Hereby sell, assign and transfer to **Infineon Technologies AG**, a corporation organized and existing under the laws of Germany, having its principal place of business at St.-Martin-Str. 53, D-81669 München, Germany, hereinafter "Assignee", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in U.S. Patent application serial number 11/680,881 filed March 1, 2007 and entitled:

POWER SEMICONDUCTOR MODULE

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, it successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Full name of joint inventor

Inventor's Signature

Date

THOMAS NUEBEL

Thomas Witel 2007-04-20

AUS01:460907.1

PATENT

REEL: 019357 FRAME: 0614

POWER SEMICONDUCTOR MODULE

Full name of joint inventor

Inventor's Signature

Date

OLIVER SCHILLING

AUS01:460907.1

PATENT

REEL: 019357 FRAME: 0615

POWER SEMICONDUCTOR MODULE

Full name of joint inventor

Inventor's Signature

Date

REINHOLD SPANKE

2007-04-20

AUS01:460907.1

RECORDED: 05/30/2007

3/3

PATENT REEL: 019357 FRAME: 0616